Thermoelectric Module Specifications

| Material Specifications (27 °C hot side temperature) | Material Specifications (50 °C hot side temperature) | Module material specifications are nominal values based on the hot-side temperature indicated. Thermoelectric material parameter tolerance is +/-10%.

- **Vmax (V)**: 16.7 | 18.5
- **Imax (A)**: 6.3 | 6.3
- **Qmax (W)**: 65.0 | 71.3
- **DTmax (°C)**: 74 | 84

In no case should the module temperature be allowed to exceed its maximum operation/storage temperature.

- **Operation/storage temperature**: -40 °C to +80 °C

Please review all product and technical information, Thermoelectric Module Mounting Procedure, parameter definitions, FAQs, and ordering information posted on our website before purchasing or using this product.

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Optional Features and Notes:

- Width, A (mm): 40 +0.5/-0.2
- Width, B (mm): 40 +0.5/-0.2
- Height, H (mm): 3.9 ±0.05
- Flatness, F (mm): 0.02
- Parallelism, P (mm): 0.03
- Wire Size, WS (mm²): 0.35
- Wire Length, WL (mm): 120

Add "P" to part number for sealing module with epoxy potting.

Performance graphs include thermal resistance of substrates.
Unpotted HP-127-1.4-1.5-74 at a hot-side temperature of 30 °C

Note: All specifications subject to change without notice. © 2018 TE Technology, Inc.
Potted HP-127-1.4-1.5-74 at a hot-side temperature of 30 °C
Unpotted HP-127-1.4-1.5-74 at a hot-side temperature of 50 °C

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Potted HP-127-1.4-1.5-74 at a hot-side temperature of 50 °C
Unpotted HP-127-1.4-1.5-74 at a hot-side temperature of 70 °C
Potted HP-127-1.4-1.5-74 at a hot-side temperature of 70 °C